HFA08TA60C

Vishay High Power Products



HEXFRED® Ultrafast Soft Recovery Diode, 2 x 4 A

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	Ι _R = 100 μΑ		600	-	-	
Maximum forward voltage		I _F = 4.0 A	See fig. 1	-	1.5	1.8	V
	V _{FM}	I _F = 8.0 A		-	1.8	2.2	
		I _F = 4.0 A, T _J = 125 °C		-	1.4	1.7	
Maximum reverse leakage current	,	$V_R = V_R$ rated	See fig. 2	-	0.17	3.0	- μΑ
	I _{RM}	$T_J = 125 ^{\circ}\text{C}, V_R = 0.8 \text{x} V_R \text{rated}$		-	44	300	
Junction capacitance	C _T	V _R = 200 V	See fig. 3	=	4.0	8.0	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body		=	8.0	=	nH

DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5, 6 and 16	t _{rr}	$I_F = 1.0 \text{ A}, dI_F/dt = 200$) A/μs, V _R = 30 V	-	17	-	ns
	t _{rr1}	T _J = 25 °C	$I_F = 4.0 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	28	42	
	t _{rr2}	T _J = 125 °C		-	38	57	
Peak recovery current See fig. 7 and 8	I _{RRM1}	T _J = 25 °C		-	2.9	5.2	А
	I _{RRM2}	T _J = 125 °C		-	3.7	6.7	
Reverse recovery charge See fig. 9 and 10	Q _{rr1}	T _J = 25 °C		-	40	60	nC
	Q _{rr2}	T _J = 125 °C		-	70	105	
Peak rate of fall of recovery current during t _b See fig. 11 and 12	dI _{(rec)M} /dt1	T _J = 25 °C		-	280	-	A/µs
	dI _{(rec)M} /dt2	T _J = 125 °C		-	235	-	- Ανμδ

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Thermal resistance, junction to case	R _{thJC}		-	-	5.0	
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	80	K/W
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-220AB	HFA08TA60C			



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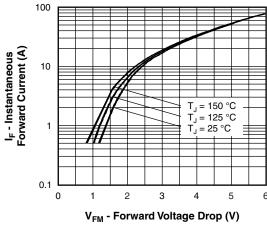


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

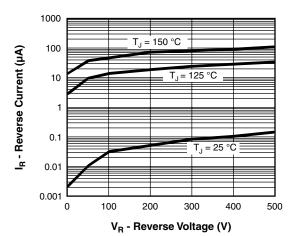


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

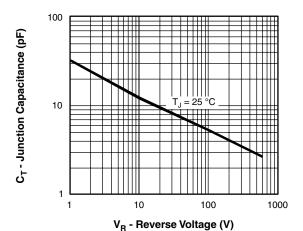


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

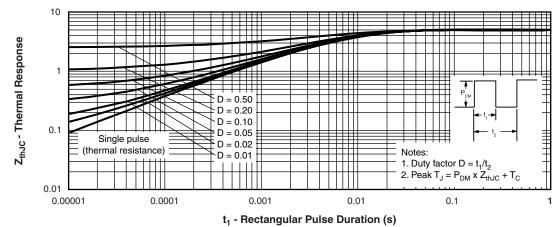


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

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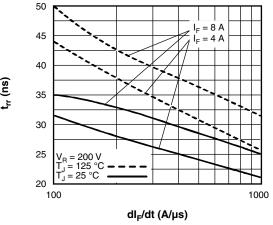


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt

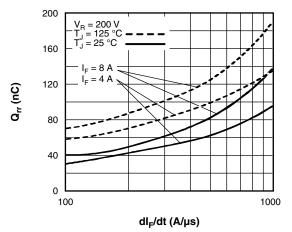


Fig. 7 - Typical Stored Charge vs. dl_F/dt

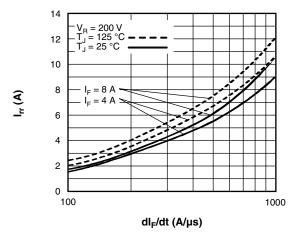


Fig. 6 - Typical Recovery Current vs. dl_F/dt

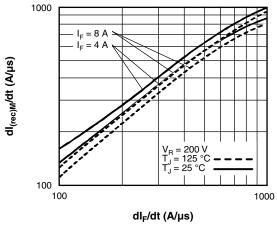


Fig. 8 - Typical $dl_{(rec)M}/dt$ vs. dl_F/dt



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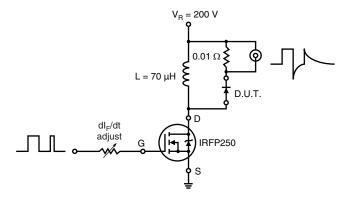
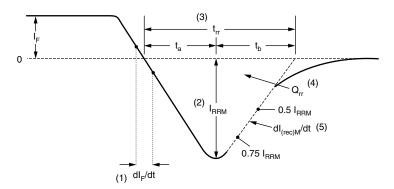


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RBM}$ and 0.50 $\rm I_{RBM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

LINKS TO RELATED DOCUMENTS				
Dimensions	http://www.vishay.com/doc?95222			
Part marking information	http://www.vishay.com/doc?95225			



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